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FIG. 1

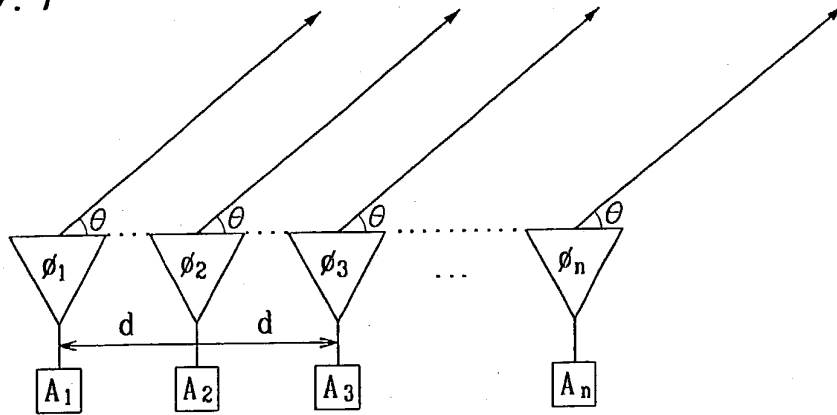


FIG. 2A

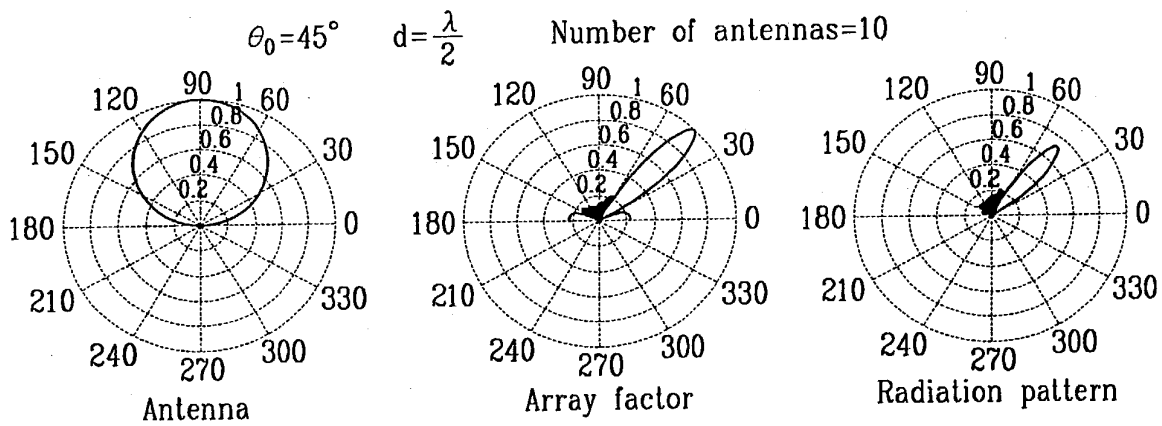
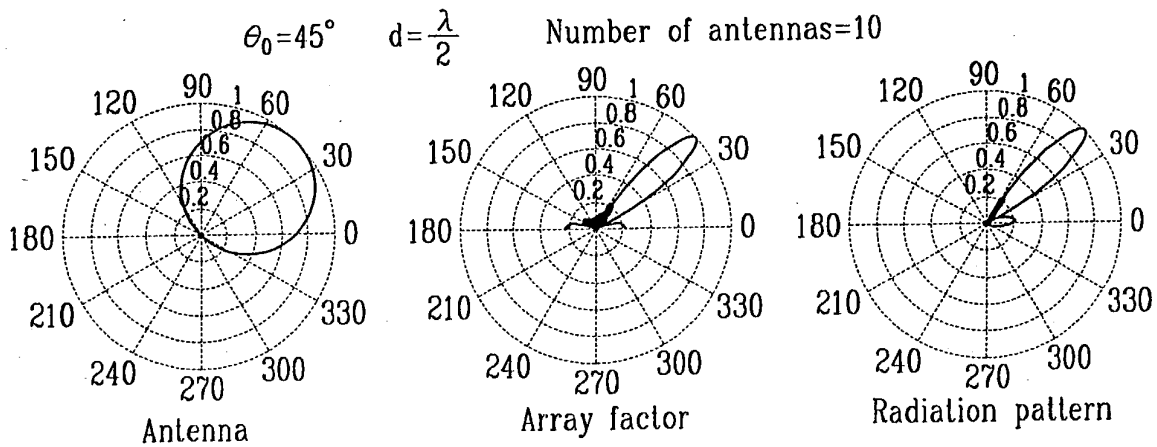


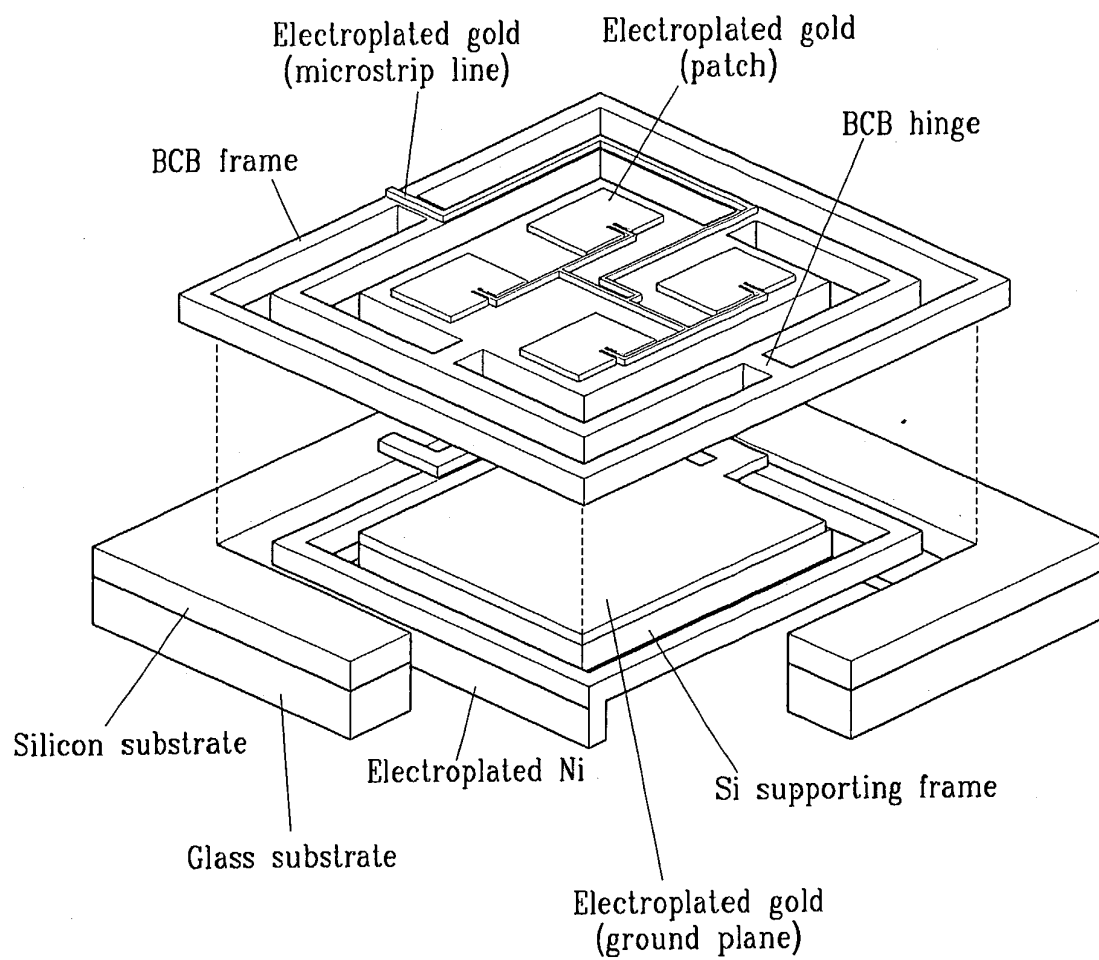
FIG. 2B



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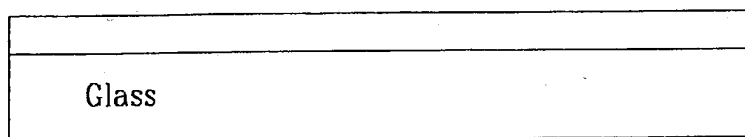
FIG. 3



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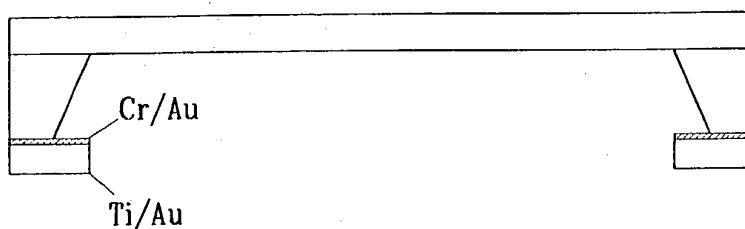
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FIG. 4A



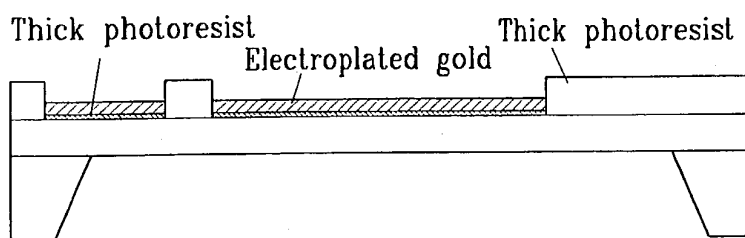
- * Anodic bonding of glass & silicon
- * Thinning of silicon using KOH
- * CMP of silicon

FIG. 4B



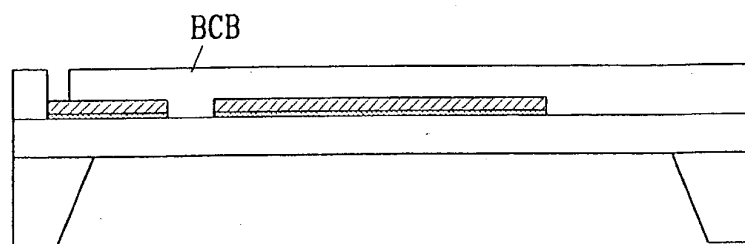
- * Cr/Au deposition
- * Photolithography #1
- * Au/Cr etch
- * Hardbake of photoresist
- * Glass etching

FIG. 4C



- * 1st seed layer deposition
- * Photolithography #2
- * Electroplating

FIG. 4D

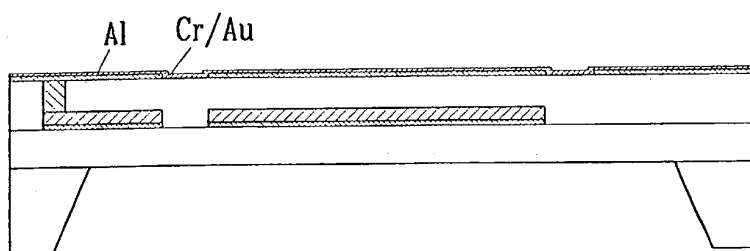


- * PR strip
- * Seed layer etching
- * BCB coating & baking
- * BCB patterning

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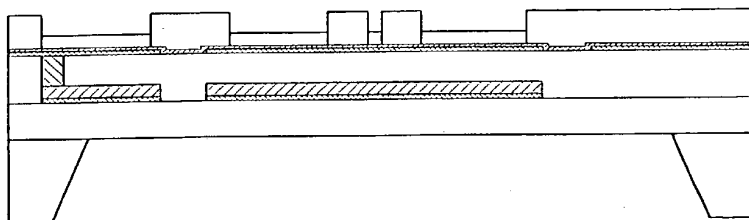
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FIG. 4E



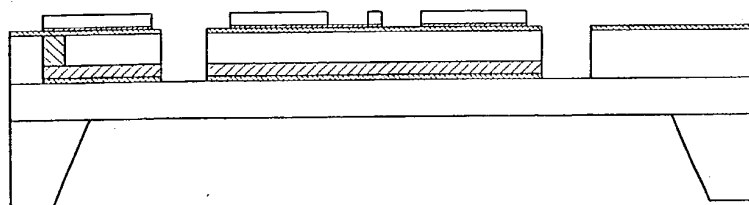
- * Au electroplating (for via)
- * Al mask deposition
- * Photolithography #3
- * Al etching
- * 2nd seed layer deposition

FIG. 4F



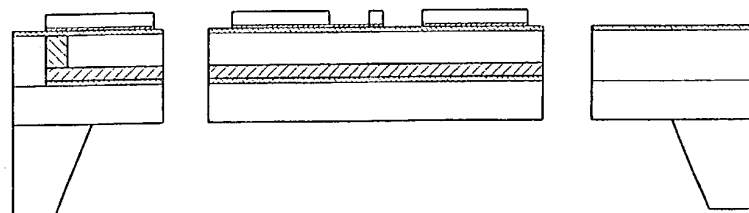
- * Photolithography #4
- * Au electroplating

FIG. 4G



- * PR strip
- * Seed layer etching
- * RIE of BCB

FIG. 4H



- * Silicon deep RIE

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FIG. 5

